

IN THE CLAIMS:

(1) Please amend Claim 1 as follows:

1. (Twice amended) An integrated circuit comprising:
a substrate;
a plurality of bond pads formed above the substrate; and
a first electrically isolated conductive trace formed at an outer region of the substrate and
coupled to at least two of the plurality of bond pads.

(2) Please amend Claim 10 as follows:

10. (Twice amended) An integrated circuit comprising:
a substrate;
a plurality of bond pads; and
an electrically isolated conductive tester runner formed on the substrate and around the
plurality of bond pads, the isolated conductive tester runner electrically coupled to at least two of
the plurality of bond pads.